

8. (CURRENTLY AMENDED) The mounting arrangement of any of the previous claims~~claim~~ 1, characterised in that it includes further comprising an electrically conductive area or pad-(12) for mounting said laser source-(2) as well as a driver-(3) for said laser source-(2), and in that said submount-(S) has an outer surface-(S') and a recess-(13) recessed with respect to said outer surface-(S'), wherein at least part of said laser driver-(3) is arranged in said recess-(13) so that the driver has an end surface extending from the recess substantially flush with said conductive pad-(12) for mounting said laser source-(2).

**REMARKS**

The specification has been amended to include headings in accordance with US practice.

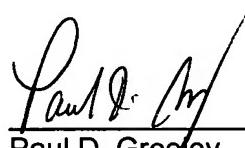
The Abstract of the Disclosure has been amended to eliminate reference numbers and to comply with MPEP 608.01(b).

The claims have been amended to removed all multiply dependencies therefrom and to place them into proper U.S. format.

Consideration and allowance of application is respectfully requested.

Respectfully submitted,

8-5-03  
Date

  
\_\_\_\_\_  
Paul D. Greeley  
Attorney for Applicant(s)  
Registration No. 31,019  
Ohlandt, Greeley, Ruggiero & Perle, L.L.P.  
One Landmark Square, 10<sup>th</sup> Floor  
Stamford, CT 06901-2682  
(203) 327-4500

On page 3, between lines 20 and 21, insert --- **SUMMARY OF THE INVENTION** ---.

On page 4, between lines 29 and 30, insert --- **BRIEF DESCRIPTION OF THE DRAWINGS** ---.

On page 5, between lines 2 and 3, insert --- **DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENT** ---.

### **In The Abstract**

Please amend the abstract as follows:

**"A mounting arrangement for high-frequency electro-optical components"**

### **ABSTRACT OF THE DISCLOSURE**

An auxiliary component such as a bias inductance-(6) associated with a laser source-(2) is mounted generally "upright", that is with its major dimension substantially orthogonal to the general plane of the submount-(S) supporting both the laser-(2) and the auxiliary component-(6). The inductor-(6) is preferably mounted at a location displaced laterally with respect to the lasing direction-(X) of the laser source. The arrangement preferably includes a submount-(S) with a recess-(13) and at least part of the laser driver is arranged in the recess so that the driver-(3) has an end surface extending from the recess substantially flush with the pad-(12) for mounting the laser source. The arrangement minimises surface occupation as well as RF and EMI parasitic effects related to wirebonding.

(Figure 2)

### **In The Claims**

Please amend the claims as follows:

1. (CURRENTLY AMENDED) A mounting arrangement for a laser source-(2) and at least one auxiliary component-(6) associated therewith, said at least one auxiliary component having a major dimension, said laser source-(2) and said auxiliary component-(6) being mounted on a submount-(S) having a general plane of extension, characterised in thatwherein said at least one auxiliary component-(6) is mounted with said major dimension substantially orthogonal to said general plane of said submount-(S).

2. (CURRENTLY AMENDED) The mounting arrangement of claim 1, characterised in thatwherein said auxiliary component is a bias inductance-(6) for said laser source-(2).

3. (CURRENTLY AMENDED) The mounting arrangement of either of claims 1 or 2, characterised in thatwherein said laser source has a lasing direction-(X) and said auxiliary component is displaced laterally with respect to said lasing direction-(X) of said laser source-(2).

4. (CURRENTLY AMENDED) The mounting arrangement of claim 3, characterised in thatwherein said laser source-(2) includes front-(2a) and back-(2b) lasing facets aligned along said lasing direction-(X), said auxiliary component-(6) has a surface exposed to radiation from said back facet-(2b) of the laser source-(2), and in that said surface is tilted laterally with respect to said lasing direction-(X) so that radiation from said laser back facet-(2b) along said lasing direction-(X) is reflected away from such direction.

5. (CURRENTLY AMENDED) The mounting arrangement of any of the previous claimsof claim 1, characterised in thatwherein said at least one auxiliary component-(6) is mounted onto said submount-(3) by means of conductive glue-(15).

6. (CURRENTLY AMENDED) The mounting arrangement of any of the previous claimsclaim 1, characterised in thatwherein said at least one auxiliary component-(6) is in the form of an SMD component.

7. (CURRENTLY AMENDED) The mounting arrangement of any of the previous claimsclaim 1, characterised in thatfurther comprising it includes an electrically conductive area or pad-(12) onto which both said laser source-(2) and said auxiliary component-(6) are mounted.